	Туре	L#	Hits	Search Text	DBs
1	BRS	L1	1737	257/737.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1647	257/738.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1214	257/780.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	1857	257/787.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	1914	257/773.ccls.	US-PGPUB; USPAT; USOCR
6	BRS	L6	1518	257/786.ccls.	US-PGPUB; USPAT; USOCR
7	BRS	L7 ·	2402	257/778.ccls.	US-PGPUB; USPAT; USOCR
8	BRS	L8	3199	Chip adj scale adj	US-PGPUB; USPAT; USOCR
9	BRS	L9	57	, ,	US-PGPUB; USPAT; USOCR
10	BRS	L10	33	` •	US-PGPUB; USPAT; USOCR
11	BRS	L11	18	, ,	US-PGPUB; USPAT; USOCR

	Туре	L#	Hits	Search Text	DBs
12	BRS	L12	33	, ,	US-PGPUB; USPAT; USOCR
13	BRS	L13	73	, ,	US-PGPUB; USPAT; USOCR
14	BRS	L14	1357	257/692.ccls.	US-PGPUB; USPAT; USOCR
15	BRS	L15	1102	257/750.ccls.	US-PGPUB; USPAT; USOCR
16	BRS	L16	31	, ,	US-PGPUB; USPAT; USOCR
17	BRS	L17	9	L15 and resin and (wiring or conducting) and first adj (electrode or terminal)	USPAT;
18	BRS	L18	235	257/737.ccls.	EPO; JPO; DERWENT; IBM_TDB
19	BRS	L19	129	257/778.ccls.	EPO; JPO; DERWENT; IBM_TDB
20	BRS	L20	449	257/773.ccls.	EPO; JPO; DERWENT; IBM_TDB
21	BRS	L21	465	257/692.ccls.	EPO; JPO; DERWENT; IBM_TDB
22	BRS	L22	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB